RoHS

COMPLIANT HALOGEN

FREE





High Temperature (245 °C) Thick Film Chip Resistor



DESIGN SUPPORT TOOLS

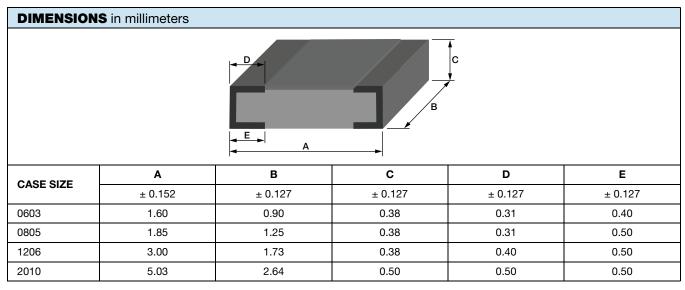
click logo to get started

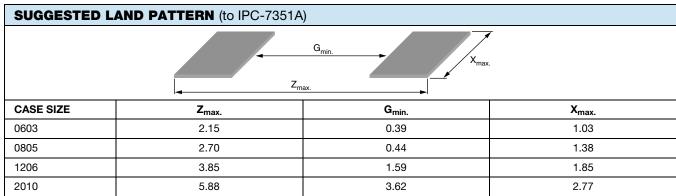


FEATURES

- High temperature (245 °C)
- Large ohmic value range 0.1 Ω to 100 M Ω
- Operating temperature range (-55 °C to +230 °C)
- SMD wraparound chip resistor
- Storage temperature range (-55 °C to +245 °C)
- \bullet Gold terminations for HMP process (< 1 μ m thick) for temperature up to 245 $^{\circ}C$
- Tin / silver terminations for operating temperature up to 200 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

For applications such as down hole applications or aircraft breaking systems, the need for parts able to withstand very severe conditions (temperature as high as 230 °C powered or up to 245 °C un-powered) has leaded Vishay Sfernice to push out the limit of the thick film technology. Designers might read the application note "Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chips Resistors and Arrays (P, PRA etc.) (High Temperature Applications)" (www.vishay.com/doc?53047) in conjunction with this data sheet to help them to properly design their PCBs and get the best performances of the CHPHT. Vishay Sfernice R&D engineers will be willing to support any customer design considerations.





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STANDARD ELECTRICAL SPECIFICATIONS							
MODEL	SIZE	RESISTANCE RANGE	RATED POWER Pn W (at 230 °C)	LIMITING ELEMENT VOLTAGE V	MAX. OVERLOAD VOLTAGE V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C
CHPHT	0603	0.1 to 25M	0.0125	50	100	1, 2, 5	100, 200
CHPHT	0805	0.1 to 25M	0.02	150	300	1, 2, 5	100, 200
CHPHT	1206	0.1 to 50M	0.025	200	400	1, 2, 5	100, 200
CHPHT	2010	0.1 to 100M	0.1	200	400	1, 2, 5	100, 200

CLIMATIC SPECIFICATIONS				
Operating temperature range	-55 °C to +230 °C			
Storage temperature range	-55 °C to +245 °C			

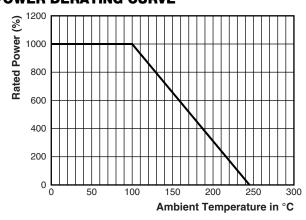
MECHANICAL SPECIFICATIONS			
Substrate	Alumina		
Technology	Thick film (Ruthenium oxyde)		
Protection	$0.5~\Omega < R < 100~\text{M}\Omega$: double organic coating $R \le 0.5~\Omega$: overglaze protection (no organic coating)		
Terminations	N (W/A): SnAg over nickel barrier for temperature up to 200 °C G (W/A) type: Gold (< 1 µm) over nickel barrier for temperature up to 245 °C		

Note

 Refer to Application Note "Guidelines for Vishay Sfernice Resistive and Inductive Components" (document number: 52029) for recommended reflow profile. Profile #3 applies

BEST TOL. AND TCR VERSUS OHMIC VALUE					
TIGHTEST OHMIC BEST TOLERANCE VALUES ppm/					
1 % (F)	5 Ω < R < 10M	100 (K)			
2 % (G)	$1 \Omega < R < R \text{ max}.$	200 (L)			
5 % (J)	$0.1 \Omega < R < R \text{ max}.$	200 (L)			

POWER DERATING CURVE



PACKAGING

ESD packaging available: Waffle pack and plastic tape and reel (low conductivity). Paper tapes available on request (ESD only). (For 0603, 0805, and 1206 only.)

	NUMBER O			
SIZE	WAFFLE	TAPE AN	TAPE WIDTH	
	PACK	MIN.	MAX.	
0603	100	100	5000	
0805	100	100	4000	8 mm
1206	140	100	4000	0 111111
2010	60		2000	

PACKAGING RULES

Waffle Pack

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover.

To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code

Tape and Reel

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided.

When several reels are needed for ordered quantity within MOQ and maximum reel capacity: Please consult Vishay Sfernice for specific ordering code



POPULAR OPTIONS

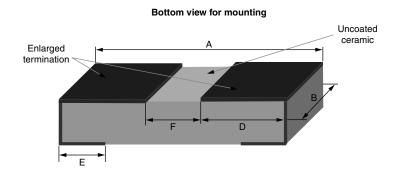
For any option it is recommended to consult Vishay Sfernice for availability first.

Option: Enlarged terminations:

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heat sinks (see application note: "Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film" (www.vishay.com/doc?53048).

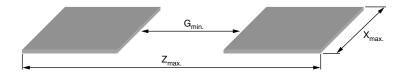
Option to order: 0063 (applies to size 1206/2010).

DIMENSIONS (Option 0063) in millimeters



	Α	В	E	D	F		
CASE SIZE	MAX. TOL. +0.152 MIN. TOL. -0.152	MAX. TOL. +0.127 MIN. TOL. -0.127	MAX. TOL. +0.13 MIN. TOL. -0.13	MAX. TOL. +0.13 MIN. TOL. -0.13			
	NOMINAL	NOMINAL	NOMINAL	NOMINAL	NOMINAL	MIN.	MAX.
1206	3.06 (0.120)	1.60 (0.063)	0.40 (0.016)	1.22 (0.048)	0.63 (0.024)	0.50 (0.020)	0.76 (0.030)
2010	5.08 (0.200)	2.54 (0.100)	0.48 (0.019)	2.23 (0.088)	0.63 (0.024)	0.50 (0.020)	0.76 (0.030)

SUGGESTED LAND PATTERN (Option 0063)



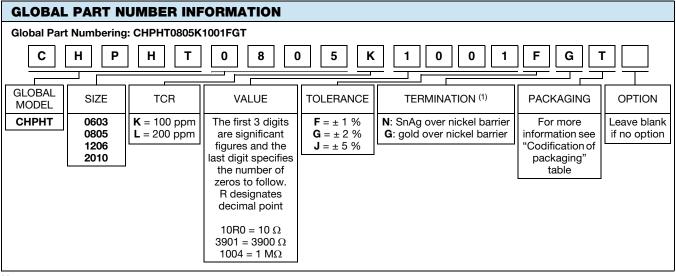
CHIP SIZE	DIMENSIONS (in millimeters)			
CHIP SIZE	Z _{max.}	G _{min.}	X _{max.}	
1206	3.91 (0.154)	0.50 (0.020)	1.73 (0.068)	
2010	5.93 (0.233)	0.50 (0.020)	2.67 (0.105)	



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PERFORMANCE					
TESTS	CONDITIONS	REQUIREMENTS	TYPICAL VALUES AND DRIFTS		
Termination adhesion	5N for 10 s	± (0.25 % + 0.05 Ω)	< ± 0.1 %		
Resistance to solder heat	Immersion 10 s in Sn/Pb 60/40 at +260 °C	± (0.25 % + 0.05 Ω)	< ± 0.1 %		
Rapid temperature change	5 cycles -55 °C to +155 °C	\pm (0.25 % + 0.05 Ω)	< ± 0.1 %		
Climatic sequence	Phase A dry heat Phase B damp heat Phase C cold -55 °C Phase D damp heat 5 cycles	± (1 % + 0.05 Ω)	< ± 0.2 %		
Humidity (steady state)	56 days	± (1 % + 0.05 Ω)	< ± 0.2 %		
Moisture resistance	AEC-Q200 85 °C / 85 % RH / Pn 1000 h	3 % + 0.05 Ω	Max. < 3 % + 0.05 Ω		
Short time overload	6.25 Pn for 2 s	\pm (0.25 % + 0.05 Ω)	< ± 0.1 %		
Load life	1000 h at rated power at 230 °C	-	1 % max.		
Shelf life	1000 h at 245 °C	-	1 % max.		



Note

⁽¹⁾ N terminations for temperature up to 200 °C G terminations for temperature up to 230 °C



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CODIFICATION OF PACKAGING					
WAFFLE PACK	WAFFLE PACK				
W	100 min., 1 mult				
WA	100 min., 100 mult (available only in size 1206)				
PLASTIC TAPE (Standard for all s	sizes)				
Т	100 min., 1 mult				
TA	100 min., 100 mult				
ТВ	250 min., 250 mult				
TC	500 min., 500 mult				
TD	1000 min., 1000 mult				
TE	2500min., 2500 mult				
TF	Full tape (quantity depending on size of chips)				
PAPER TAPE (Available for 0603,	0805, and 1206. Please consult Vishay Sfernice for other sizes)				
PT	100 min., 1 mult				
PA	100 min., 100 mult				
PB	250 min., 250 mult				
PC	500 min., 500 mult				
PD	1000 min., 1000 mult				
PE	2500min., 2500 mult				
PF	Full tape (quantity depending on size of chips)				

CODIFICATION OF OPTIONS ON TWO DIGITS					
OPTION	OPTION 2 DIGITS	OPTION	OPTION 2 DIGITS		
		0126	1A		
0099	99	0127	1B		
0100	0A	0128	1C		
0101	0B				
0102	0C	0320	8M		
0103	0D	0321	8N		
0104	0E	0322	80		
0105	0F	0323	8P		
		0324	8Q		
0124	0Y	0325	8R		
0125	0Z				

CODIFICATION OF SIZES					
CODE 18	CODE 40	CODE 18	CODE 40		
7	02016	М	22		
8	0302	N	33		
9	0402	0	44		
А	0502	Р	55		
В	0505	Q	515		
С	0603	R	48		
D	0805	S	408		
E	1005	Т	816		
F	1010	U	914		
G	1020	V	073		
Н	1206	W	074		
1	1505	Х	100		
J	2010	Y	135		
K	2208	Z	182		
L	2512				



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